

### CMOS, +1.8 V to +5.5 V/ $\pm$ 2.5 V, 2.5 $\Omega$ Low-Voltage, 8-/16-Channel Multiplexers

### ADG706/ADG707

#### **FEATURES**

+1.8 V to +5.5 V Single Supply  $\pm 2.5$  V Dual Supply 2.5  $\Omega$  ON Resistance 0.5  $\Omega$  ON Resistance Flatness 100 pA Leakage Currents 40 ns Switching Times Single 16-to-1 Multiplexer ADG706 Differential 8-to-1 Multiplexer ADG707 28-Lead TSSOP Package Low-Power Consumption TTL/CMOS-Compatible Inputs

APPLICATIONS
Data Acquisition Systems
Communication Systems
Relay Replacement
Audio and Video Switching
Battery-Powered Systems

#### **GENERAL DESCRIPTION**

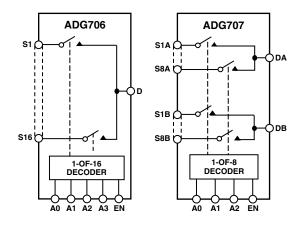
The ADG706 and ADG707 are low-voltage, CMOS analog multiplexers comprising 16 single channels and eight differential channels, respectively. The ADG706 switches one of 16 inputs (S1–S16) to a common output, D, as determined by the 4-bit binary address lines A0, A1, A2, and A3. The ADG707 switches one of eight differential inputs to a common differential output as determined by the 3-bit binary address lines A0, A1, and A2. An EN input on both devices is used to enable or disable the device. When disabled, all channels are switched OFF.

Low-power consumption and operating supply range of 1.8~V to 5.5~V make the ADG706 and ADG707 ideal for battery-powered, portable instruments. All channels exhibit break-before-make switching action preventing momentary shorting when switching channels. These devices are also designed to operate from a dual supply of  $\pm 2.5~V$ .

These multiplexers are designed on an enhanced submicron process that provides low-power dissipation yet gives high switching speed, very low ON resistance, and leakage currents. ON resistance is in the region of a few ohms and is closely matched between switches and very flat over the full signal range. These parts can operate equally well as either multiplexers or demultiplexers and have an input signal range that extends to the supplies.

The ADG706 and ADG707 are available in small 28-lead TSSOP packages.

#### FUNCTIONAL BLOCK DIAGRAMS



#### PRODUCT HIGHLIGHTS

- 1. Single-/dual-supply operation. The ADG706 and ADG707 are fully specified and guaranteed with 3 V and 5 V single-supply and  $\pm 2.5$  V dual-supply rails.
- 2. Low ON resistance (2.5  $\Omega$  typical)
- 3. Low-power consumption (<0.01  $\mu$ W)
- 4. Guaranteed break-before-make switching action
- 5. Small 28-lead TSSOP package

## $\textbf{ADG706/ADG707-SPECIFICATIONS}^{1} \ (\textbf{V}_{DD} = 5 \ \textbf{V} \pm 10\%, \ \textbf{V}_{SS} = 0 \ \textbf{V}, \ \textbf{GND} = 0 \ \textbf{V}, \ \textbf{unless otherwise noted.})$

Parameter	25°C	-40°C to +85°C	Unit	Test Conditions/Comments
ANALOG SWITCH				
Analog Signal Range		$0~\mathrm{V}$ to $\mathrm{V}_{\mathrm{DD}}$	V	
ON Resistance (R <sub>ON</sub> )	2.5		Ω typ	$V_S = 0 \text{ V to } V_{DD}, I_{DS} = 10 \text{ mA};$
( 617	4.5	5	Ω max	Test Circuit 1
ON Resistance Match Between		0.3	Ω typ	$V_S = 0 \text{ V to } V_{DD}, I_{DS} = 10 \text{ mA}$
Channels ( $\Delta R_{ON}$ )		0.8	Ω max	5 55, 55
ON Resistance Flatness (R <sub>FLAT(ON)</sub> )	0.5		Ω typ	$V_S = 0 \text{ V to } V_{DD}, I_{DS} = 10 \text{ mA}$
		1.2	Ω max	5 25 26
LEAKAGE CURRENTS				V <sub>DD</sub> = 5.5 V
Source OFF Leakage I <sub>S</sub> (OFF)	±0.01		nA typ	$V_D = 4.5 \text{ V/1 V}, V_S = 1 \text{ V/4.5 V};$
	±0.1	±0.3	nA max	Test Circuit 2
Drain OFF Leakage I <sub>D</sub> (OFF)	±0.01	_0.5	nA typ	$V_D = 4.5 \text{ V/1 V}, V_S = 1 \text{ V/4.5 V};$
ADG706	±0.4	±1.5	nA max	Test Circuit 3
ADG700 ADG707	±0.2	±1.5	nA max	rest direction
Channel ON Leakage I <sub>D</sub> , I <sub>S</sub> (ON)	$\pm 0.21$	<u>- 1</u>	nA typ	$V_D = V_S = 1 \text{ V, or } 4.5 \text{ V;}$
ADG706	$\pm 0.01$ $\pm 0.4$	±1.5	nA max	Test Circuit 4
ADG700 ADG707	$\pm 0.4 \\ \pm 0.2$	±1.5 ±1	nA max	10st Official 4
DIGITAL INPUTS	-0.2	÷.1	III I III III	
Input High Voltage, V <sub>INH</sub>		2.4	V min	
Input Ingil Voltage, $V_{INL}$ Input Low Voltage, $V_{INL}$		0.8	V max	
Input Cow Voltage, V <sub>INL</sub> Input Current		0.6	V IIIax	
I <sub>INL</sub> or I <sub>INH</sub>	0.005		IIA typ	$V_{IN} = V_{INI}$ or $V_{INH}$
INL OI INH	0.005	±0.1	μΑ typ μΑ max	VIN - VINL OI VINH
C <sub>IN</sub> , Digital Input Capacitance	5	±0.1	pF typ	
DYNAMIC CHARACTERISTICS <sup>2</sup>	-		prityp	
	40		no tro	$R_L = 300 \Omega$ , $C_L = 35 pF$ , Test Circuit 5
t <sub>TRANSITION</sub>	40	60	ns typ	$V_{S1} = 3 \text{ V/O V}, V_{S16} = 0 \text{ V/3 V}$
Proofs Potors Malta Time Dolay +	30	00	ns max	$R_{L} = 300 \Omega, C_{L} = 35 pF;$
Break-Before-Make Time Delay, t <sub>D</sub>	30	1	ns typ ns min	$V_S = 3 \text{ V}$ , Test Circuit 6
+ (EN)	32	1		$R_L = 300 \Omega$ , $C_L = 35 pF$ ;
$t_{ON}$ (EN)	32	50	ns typ ns max	$V_S = 3 \text{ V}$ , Test Circuit 7
t <sub>OFF</sub> (EN)	10	50		$R_L = 300 \Omega$ , $C_L = 35 pF$ ;
toff (LIV)	10	14	ns typ ns max	$V_S = 3 \text{ V, Test Circuit } 7$
Charge Injection	±5	14	pC typ	$V_S = 3 \text{ V}$ , Test Chedit $I$ $V_S = 1 \text{ V}$ , $R_S = 0 \Omega$ , $C_L = 1 \text{ nF}$ ;
Charge injection	- 3		pc typ	Test Circuit 8
OFF Isolation	-60		dB typ	$R_{L} = 50 \Omega$ , $C_{L} = 5 pF$ , $f = 10 MHz$ ;
	-80		dB typ	$R_L = 50 \Omega$ , $C_L = 5 pF$ , $f = 1 MHz$ ;
			u2 1,7 p	Test Circuit 9
Channel-to-Channel Crosstalk	-60		dB typ	$R_L = 50 \Omega$ , $C_L = 5 pF$ , $f = 10 MHz$ ;
Chamier to Chamier Crosstan	-80		dB typ	$R_L = 50 \Omega$ , $C_L = 5 pF$ , $f = 1 MHz$ ;
			*JP	Test Circuit 10
-3 dB Bandwidth				
ADG706	25		MHz typ	$R_L = 50 \Omega$ , $C_L = 5 pF$ , Test Circuit 9
ADG707	36		MHz typ	$R_L = 50 \Omega$ , $C_L = 5 pF$ , Test Circuit 9
$C_S$ (OFF)	13		pF typ	f = 1 MHz
C <sub>D</sub> (OFF)				
ADG706	180		pF typ	f = 1  MHz
ADG707	90		pF typ	f = 1  MHz
$C_D, C_S (ON)$				
ADG706	200		pF typ	f = 1  MHz
ADG707	100		pF typ	f = 1 MHz
POWER REQUIREMENTS				V <sub>DD</sub> = 5.5 V
	1		1	
I <sub>DD</sub>	0.001		μA typ	Digital Inputs = $0 \text{ V or } 5.5 \text{ V}$

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#### NOTES

¹Temperature range is −40°C to +85°C.

<sup>&</sup>lt;sup>2</sup>Guaranteed by design, not subject to production test.

Specifications subject to change without notice.

# $\label{eq:special_special} SPECIFICATIONS^{1} \; (v_{DD} = 3 \; v \; \pm \; 10\%, \; v_{SS} = 0 \; v, \; \text{GND} = 0 \; v, \; \text{unless otherwise noted.})$

		−40°C		
Parameter	25°C	to +85°C	Unit	Test Conditions/Comments
ANALOG SWITCH				
Analog Signal Range		$0~\mathrm{V}$ to $\mathrm{V}_{\mathrm{DD}}$	V	
ON Resistance (R <sub>ON</sub> )	6		Ω typ	$V_S = 0 \text{ V to } V_{DD}, I_{DS} = 10 \text{ mA};$
	11	12	Ω max	Test Circuit 1
ON Resistance Match Between		0.4	Ω typ	$V_S = 0 \text{ V to } V_{DD}, I_{DS} = 10 \text{ mA}$
Channels ( $\Delta R_{ON}$ )		1.2	Ω max	
ON Resistance Flatness (R <sub>FLAT(ON)</sub> )		3	Ω typ	$V_S = 0 \text{ V to } V_{DD}, I_{DS} = 10 \text{ mA}$
LEAKAGE CURRENTS				$V_{\rm DD} = 3.3 \text{ V}$
Source OFF Leakage I <sub>S</sub> (OFF)	±0.01		nA typ	$V_S = 3 \text{ V/1 V}, V_D = 1 \text{ V/3 V};$
Source off Zeamage 13 (off)	±0.1	±0.3	nA max	Test Circuit 2
Drain OFF Leakage I <sub>D</sub> (OFF)	±0.01	_0.5	nA typ	$V_S = 3 \text{ V/1 V}, V_D = 1 \text{ V/3 V};$
ADG706	$\pm 0.4$	±1.5	nA max	Test Circuit 3
ADG707	±0.2	±1.5	nA max	Test Great 5
Channel ON Leakage I <sub>D</sub> , I <sub>S</sub> (ON)	±0.01	<u>- 1</u>	nA typ	$V_S = V_D = 1 \text{ V or } 3 \text{ V};$
ADG706	$\pm 0.4$	±1.5	nA max	Test Circuit 4
ADG700 ADG707	$\pm 0.4$ $\pm 0.2$	±1.5 ±1	nA max	Test Cheurt 4
	±0.2	<u>- 1</u>	III IIIax	
DIGITAL INPUTS		• •		
Input High Voltage, V <sub>INH</sub>		2.0	V min	
Input Low Voltage, V <sub>INL</sub>		0.8	V max	
Input Current				
I <sub>INL</sub> or I <sub>INH</sub>	0.005		μA typ	$V_{IN} = V_{INL}$ or $V_{INH}$
	_	$\pm 0.1$	μA max	
C <sub>IN</sub> , Digital Input Capacitance	5		pF typ	
DYNAMIC CHARACTERISTICS <sup>2</sup>				
t <sub>TRANSITION</sub>	45		ns typ	$R_L = 300 \Omega$ , $C_L = 35 pF$ , Test Circuit 5
		75	ns max	$V_{S1} = 2 \text{ V}/0 \text{ V}, V_{S16} = 0 \text{ V}/2 \text{ V}$
Break-Before-Make Time Delay, t <sub>D</sub>	30		ns typ	$R_L = 300 \Omega, C_L = 35 pF;$
		1	ns min	$V_S = 2 V$ , Test Circuit 6
$t_{ON}$ (EN)	40		ns typ	$R_L = 300 \Omega, C_L = 35 pF;$
		70	ns max	$V_S = 2 V$ , Test Circuit 7
$t_{OFF}$ (EN)	20		ns typ	$R_L = 300 \Omega$ , $C_L = 35 pF$ ;
		28	ns max	$V_S = 2 V$ , Test Circuit 7
Charge Injection	±5		pC typ	$V_S = 1 \text{ V}, R_S = 0 \Omega, C_L = 1 \text{ nF};$
				Test Circuit 8
OFF Isolation	-60		dB typ	$R_L = 50 \Omega$ , $C_L = 5 pF$ , $f = 10 MHz$ ;
	-80		dB typ	$R_L = 50 \Omega$ , $C_L = 5 pF$ , $f = 1 MHz$ ;
				Test Circuit 9
Channel-to-Channel Crosstalk	-60		dB typ	$R_L = 50 \Omega$ , $C_L = 5 pF$ , $f = 10 MHz$ ;
	-80		dB typ	$R_L = 50 \Omega$ , $C_L = 5 pF$ , $f = 1 MHz$ ;
				Test Circuit 10
−3 dB Bandwidth				
ADG706	25		MHz typ	$R_L = 50 \Omega$ , $C_L = 5 pF$ , Test Circuit 9
ADG707	36		MHz typ	$R_L = 50 \Omega$ , $C_L = 5 pF$ , Test Circuit 9
$C_S$ (OFF)	13		pF typ	f = 1  MHz
$C_{\rm D}$ (OFF)			- /-	
ADG706	180		pF typ	f = 1  MHz
ADG707	90		pF typ	f = 1  MHz
$C_D, C_S (ON)$	1			
ADG706	200		pF typ	f = 1  MHz
ADG707	100		pF typ	f = 1  MHz
POWER REQUIREMENTS			1 31	V <sub>DD</sub> = 3.3 V
	0.001		IIA typ	$v_{DD} = 3.3 \text{ V}$ Digital Inputs = 0 V or 3.3 V
$I_{\mathrm{DD}}$	0.001	1.0	μA typ μA max	Digital Inputs – 0 v 01 3.3 v
	1	1.0	μαιπαχ	

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¹Temperature range is −40°C to +85°C.

<sup>&</sup>lt;sup>2</sup>Guaranteed by design, not subject to production test.

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 $\textbf{DUAL SUPPLY}^{1} \text{ (V}_{DD} = +2.5 \text{ V } \pm 10\%, \text{ V}_{SS} = -2.5 \text{ V } \pm 10\%, \text{ GND} = 0 \text{ V, unless otherwise noted.)}$ 

Parameter	25°C	-40°C to +85°C	Unit	Test Conditions/Comments
ANALOG SWITCH				
Analog Signal Range		$V_{SS}$ to $V_{DD}$	V	
ON Resistance (R <sub>ON</sub> )	2.5	_	$\Omega$ typ	$V_S = V_{SS}$ to $V_{DD}$ , $I_{DS} = 10$ mA;
OMP	4.5	5	Ω max	Test Circuit 1
ON Resistance Match Between		0.3	Ω typ	$V_S = V_{SS}$ to $V_{DD}$ , $I_{DS} = 10$ mA
Channels $(\Delta R_{ON})$	0.5	0.8	Ω max	V - V to V I - 10 ··· A
ON Resistance Flatness (R <sub>FLAT(ON)</sub> )	0.5	1.2	$\Omega$ typ $\Omega$ max	$V_S = V_{SS}$ to $V_{DD}$ , $I_{DS} = 10$ mA
LEAKAGE CURRENTS				$V_{DD} = +2.75 \text{ V}, V_{SS} = -2.75 \text{ V}$
Source OFF Leakage I <sub>S</sub> (OFF)	±0.01		nA typ	$V_S = +2.25 \text{ V/}-1.25 \text{ V}, V_D = -1.25 \text{ V/}+2.25 \text{ V};$
	±0.1	$\pm 0.3$	nA max	Test Circuit 2
Drain OFF Leakage I <sub>D</sub> (OFF)	±0.01		nA typ	$V_S = +2.25 \text{ V/}-1.25 \text{ V}, V_D = -1.25 \text{ V/}+2.25 \text{ V};$
ADG706	±0.4	±1.5	nA max	Test Circuit 3
ADG707	±0.2	±1	nA max	
Channel ON Leakage I <sub>D</sub> , I <sub>S</sub> (ON)	±0.01		nA typ	$V_S = V_D = +2.25 \text{ V}/-1.25 \text{ V}$ , Test Circuit 4
ADG706	±0.4	±1.5	nA max	
ADG707	±0.2	$\pm 1$	nA max	
DIGITAL INPUTS				
Input High Voltage, V <sub>INH</sub>		1.7	V min	
Input Low Voltage, V <sub>INL</sub>		0.7	V max	
Input Current				
$ ilde{I}_{ ext{INL}}$ or $ ext{I}_{ ext{INH}}$	0.005		μA typ	$V_{IN} = V_{INL}$ or $V_{INH}$
		$\pm 0.1$	μA max	
C <sub>IN</sub> , Digital Input Capacitance	5		pF typ	
DYNAMIC CHARACTERISTICS <sup>2</sup>				
t <sub>TRANSITION</sub>	40		ns typ	$R_L = 300 \Omega$ , $C_L = 35 pF$ , Test Circuit 5
11411/0111011		60	ns max	$V_{S1} = 1.5 \text{ V/0 V}, V_{S16} = 0 \text{ V/1.5 V}$
Break-Before-Make Time Delay, t <sub>D</sub>	15		ns typ	$R_L = 300 \Omega, C_L = 35 pF;$
		1	ns min	$V_S = 1.5 \text{ V}$ , Test Circuit 6
$t_{ON}$ (EN)	32		ns typ	$R_L = 300 \Omega, C_L = 35 pF;$
		50	ns max	$V_S = 1.5 \text{ V}$ , Test Circuit 7
$t_{OFF}$ (EN)	16		ns typ	$R_L = 300 \Omega, C_L = 35 pF;$
		26	ns max	$V_S = 1.5 \text{ V}$ , Test Circuit 7
Charge Injection	±8		pC typ	$V_S = 0 V, R_S = 0 \Omega, C_L = 1 nF;$ Test Circuit 8
OFF Isolation	-60		dB typ	R <sub>L</sub> = $50 \Omega$ , C <sub>L</sub> = $5 pF$ , f = $10 MHz$ ;
OTT Isolation	-80		dB typ	$R_L = 50 \Omega$ , $C_L = 5 \text{ pF}$ , $f = 10 \text{ MHz}$ , $R_L = 50 \Omega$ , $C_L = 5 \text{ pF}$ , $f = 1 \text{ MHz}$ ;
	-80		db typ	Test Circuit 9
Channel-to-Channel Crosstalk	-60		dB typ	$R_L = 50 \Omega$ , $C_L = 5 pF$ , $f = 10 MHz$ ;
	-80		dB typ	$R_L = 50 \Omega$ , $C_L = 5 pF$ , $f = 1 MHz$ ;
				Test Circuit 10
−3 dB Bandwidth				
ADG706	25		MHz typ	$R_L = 50 \Omega$ , $C_L = 5 pF$ , Test Circuit 9
ADG707	36		MHz typ	$R_L = 50 \Omega$ , $C_L = 5 pF$ , Test Circuit 9
$C_{S}$ (OFF)	13		pF typ	f = 1  MHz
$C_D$ (OFF)				
ADG706	180		pF typ	f = 1  MHz
ADG707	90		pF typ	f = 1  MHz
$C_D, C_S(ON)$				
ADG706	200		pF typ	f = 1  MHz
ADG707	100		pF typ	f = 1 MHz
POWER REQUIREMENTS				
$I_{\mathrm{DD}}$	0.001		μA typ	$V_{\rm DD} = +2.75 \text{ V}$
		1.0	μA max	Digital Inputs = 0 V or 2.75 V
$I_{SS}$	0.001		μA typ	$V_{SS} = -2.75 \text{ V}$
		1.0	μA max	Digital Inputs = 0 V or 2.75 V

NOTES

<sup>1</sup>Temperature range is -40°C to +85°C.

<sup>2</sup>Guaranteed by design, not subject to production test.

Specifications subject to change without notice.

ABSOLUTE MAXIMUM RATINGS <sup>1</sup> (T <sub>A</sub> = 25°C unless otherwise noted.)
$V_{DD}$ to $V_{SS}$
$V_{DD}$ to GND0.3 V to +7 V
$V_{SS}$ to GND +0.3 V to -3.5 V
Analog Inputs <sup>2</sup> $V_{SS}$ – 0.3 V to $V_{DD}$ + 0.3 V or
30 mA, Whichever Occurs First
Digital Inputs <sup>2</sup> $-0.3 \text{ V to V}_{DD} + 0.3 \text{ V or}$
30 mA, Whichever Occurs First
Peak Current, S or D
(Pulsed at 1 ms, 10% Duty Cycle max)
Continuous Current, S or D
Operating Temperature Range
Industrial

Storage Temperature Range65°C to +150°C
Junction Temperature 150°C
TSSOP Package
$\theta_{IA}$ Thermal Impedance 97.9°C/W
$\theta_{\rm IC}$ Thermal Impedance
Lead Temperature, Soldering (10 sec) 300°C
IR Reflow, Peak Temperature 220°C
NOTES

NOTES

<sup>1</sup>Stresses above those listed under Absolute Maximum Ratings may cause permanent damage to the device. This is a stress rating only; functional operation of the device at these or any other conditions above those listed in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability. Only one absolute maximum rating may be applied at any one time.

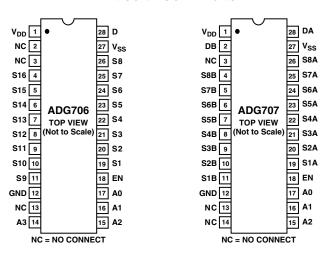
<sup>2</sup>Overvoltages at A, EN, S, or D will be clamped by internal diodes. Current should be limited to the maximum ratings given.

#### **ORDERING GUIDE**

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Model <sup>1</sup>	Temperature Range	Package Description	Package Option			
ADG706BRU	-40°C to +85°C	28-Lead Thin Shrink Small Outline Package [TSSOP]	RU-28			
ADG706BRU-REEL7	−40°C to +85°C	28-Lead Thin Shrink Small Outline Package [TSSOP]	RU-28			
ADG706BRUZ	−40°C to +85°C	28-Lead Thin Shrink Small Outline Package [TSSOP]	RU-28			
ADG706BRUZ-REEL	-40°C to +85°C	28-Lead Thin Shrink Small Outline Package [TSSOP]	RU-28			
ADG706BRUZ-REEL7	−40°C to +85°C	28-Lead Thin Shrink Small Outline Package [TSSOP]	RU-28			
ADG707BRU	−40°C to +85°C	28-Lead Thin Shrink Small Outline Package [TSSOP]	RU-28			
ADG707BRU-REEL	-40°C to +85°C	28-Lead Thin Shrink Small Outline Package [TSSOP]	RU-28			
ADG707BRUZ	-40°C to +85°C	28-Lead Thin Shrink Small Outline Package [TSSOP]	RU-28			
ADG707BRUZ-REEL7	−40°C to +85°C	28-Lead Thin Shrink Small Outline Package [TSSOP]	RU-28			

<sup>&</sup>lt;sup>1</sup> Z = RoHS Compliant Part.

#### PIN CONFIGURATIONS



#### **CAUTION**

ESD (electrostatic discharge) sensitive device. Electrostatic charges as high as 4000 V readily accumulate on the human body and test equipment and can discharge without detection. Although the ADG706/ADG707 features proprietary ESD protection circuitry, permanent damage may occur on devices subjected to high energy electrostatic discharges. Therefore, proper ESD precautions are recommended to avoid performance degradation or loss of functionality.



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Table I. ADG706 Truth Table

<b>A3</b>	A2	A1	A0	EN	ON Switch
X	X	X	X	0	NONE
0	0	0	0	1	1
0	0	0	1	1	2
0	0	1	0	1	3
0	0	1	1	1	4
0	1	0	0	1	5
0	1	0	1	1	6
0	1	1	0	1	7
0	1	1	1	1	8
1	0	0	0	1	9
1	0	0	1	1	10
1	0	1	0	1	11
1	0	1	1	1	12
1	1	0	0	1	13
1	1	0	1	1	14
1	1	1	0	1	15
1	1	1	1	1	16

X = Don't Care

Table II. ADG707 Truth Table

<b>A2</b>	A1	A0	EN	ON Switch Pair
X	X	X	0	NONE
0	0	0	1	1
0	0	1	1	2
0	1	0	1	3
0	1	1	1	4
1	0	0	1	5
1	0	1	1	6
1	1	0	1	7
1	1	1	1	8

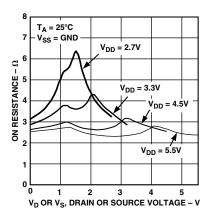
X = Don't Care

#### **TERMINOLOGY**

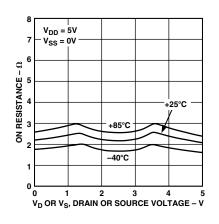
$\overline{V_{DD}}$	Most positive power supply potential	$C_{\rm D}$ (OFF)	"OFF" Switch drain capacitance. Measured with reference to ground.		
$V_{SS}$	Most negative power supply in a dual-supply application. In single-supply applications, this should be tied to ground at the device.	$C_D$ , $C_S$ (ON)	"ON" Switch capacitance. Measured with reference to ground.		
$I_{DD}$	Positive supply current	$C_{IN}$	Digital input capacitance		
$I_{SS}$	Negative supply current	t <sub>TRANSITION</sub>	Delay time measured between the 50% and		
GND	Ground (0 V) reference		90% points of the digital inputs and the switch		
S	Source terminal. May be an input or output.		"ON" condition when switching from one address state to another		
D	Drain terminal. May be an input or output.	t <sub>ON</sub> (EN)	Delay time between the 50% and 90% points		
AX	Logic control input		of the EN digital input and the Switch "ON"		
EN	Active high device enable		condition		
$V_D(V_S)$	Analog voltage on terminals D, S	t <sub>OFF</sub> (EN)	Delay time between the 50% and 90% points of the EN digital input and the Switch "OFF" condition		
$R_{ON}$	Ohmic resistance between D and S				
$\Delta R_{\mathrm{ON}}$	ON Resistance match between any two channels, i.e., $R_{ON}$ max – $R_{ON}$ min	t <sub>OPEN</sub>	"OFF" Time measured between the 80% points of both switches when switching from one		
R <sub>FLAT(ON)</sub>	Flatness is defined as the difference between the		address state to another		
	maximum and minimum value of ON resistance as measured over the specified analog signal range.	Charge Injection	Measure of the glitch impulse transferred from the digital input to the analog output during switching		
I <sub>S</sub> (OFF)	Source leakage current with the Switch "OFF"	OFF Isolation	Measure of unwanted signal coupling through		
I <sub>D</sub> (OFF)	Drain leakage current with the Switch "OFF"		an "OFF" switch		
$I_D, I_S (ON)$	Channel leakage current with the Switch "ON"	Crosstalk	Measure of unwanted signal that is coupled		
$V_{INL}$	Maximum input voltage for Logic "0"		through from one channel to another as a result of parasitic capacitance		
$V_{INH}$	Minimum input voltage for Logic "1"	Bandwidth	Frequency at which the output is attenuated		
$I_{\rm INL}(I_{\rm INH})$	Input current of the digital input	Banawiani	by 3 dB		
C <sub>S</sub> (OFF)	"OFF" Switch Source Capacitance. Measured	ON Response	Frequency response of the "ON" Switch		
	with reference to ground.	Insertion Loss	Loss due to the ON Resistance of the switch		

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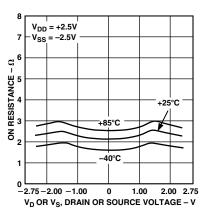
### Typical Performance Characteristics—ADG706/ADG707



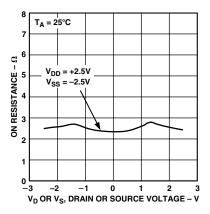
TPC 1. ON Resistance as a Function of  $V_D$  ( $V_S$ ) for Single Supply



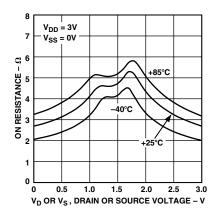
TPC 2. ON Resistance as a Function of  $V_D$  ( $V_S$ ) for Different Temperatures, Single Supply



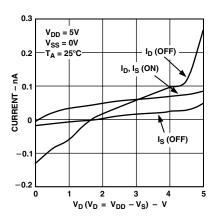
TPC 3. ON Resistance as a Function of  $V_D$  ( $V_S$ ) for Different Temperatures, Dual Supply



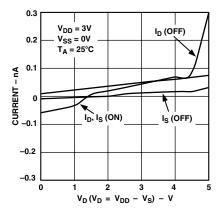
TPC 4. ON Resistance as a Function of  $V_D(V_S)$  for Dual Supply



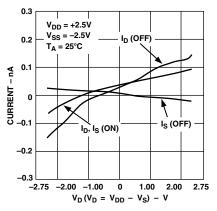
TPC 5. ON Resistance as a Function of  $V_D$  ( $V_S$ ) for Different Temperatures, Single Supply



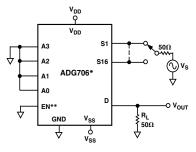
TPC 6. Leakage Currents as a Function of  $V_D$  ( $V_S$ )



TPC 7. Leakage Currents as a Function of  $V_D$  ( $V_S$ )



TPC 8. Leakage Currents as a Function of  $V_D$  ( $V_S$ )



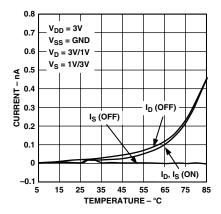
\*SIMILAR CONNECTION FOR ADG707

\*\*CONNECT TO 2.44 FOR BANDWIDTH MEASUREMENTS
OFF ISOLATION = 20LOG<sub>10</sub>(V<sub>OUT</sub>/V<sub>S</sub>)
INSERTION LOSS = 20LOG<sub>10</sub>

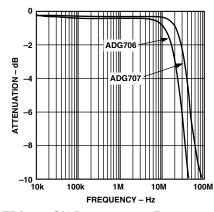
V<sub>OUT</sub> WITH SWITCH V<sub>OUT</sub> WITHOUT SWITCH V<sub>OUT</sub> W<sub>OUT</sub> W<sub>OUT</sub> WITHOUT SWITCH V<sub>OUT</sub> W<sub>OUT</sub> W

TPC 9. Leakage Currents as a Function of Temperature

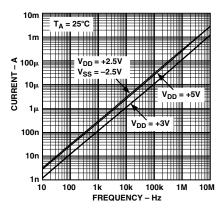
REV. B -7-



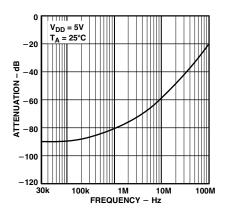
TPC 10. Leakage Currents as a Function of Temperature



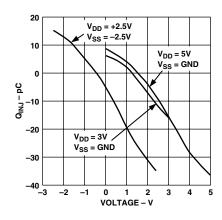
TPC 11. ON Response vs. Frequency



TPC 12. Supply Currents vs. Input Switching Frequency

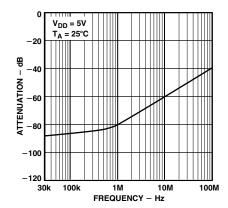


TPC 13. OFF Isolation vs. Frequency



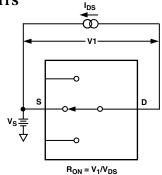
TPC 14. Charge Injection vs. Source Voltage

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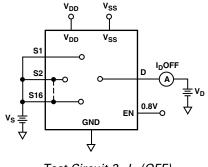


TPC 15. Crosstalk vs. Frequency

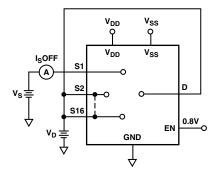
#### **TEST CIRCUITS**



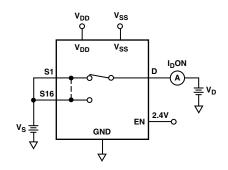
Test Circuit 1. ON Resistance



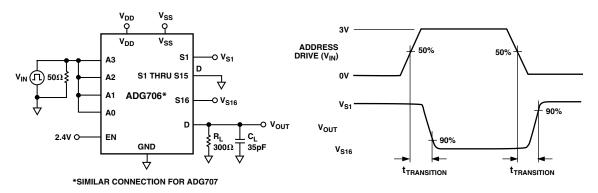
Test Circuit 3. I<sub>D</sub> (OFF)



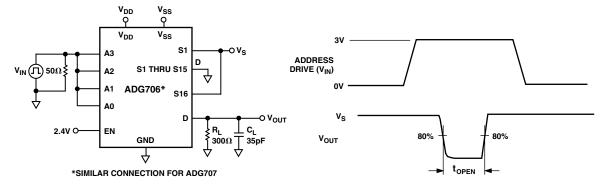
Test Circuit 2. I<sub>S</sub> (OFF)



Test Circuit 4. I<sub>D</sub> (ON)

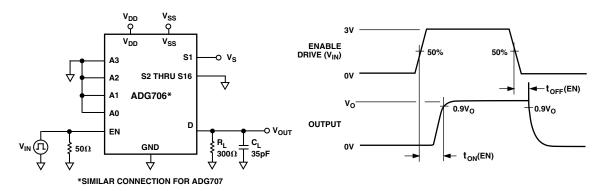


Test Circuit 5. Switching Time of Multiplexer,  $t_{TRANSITION}$ 

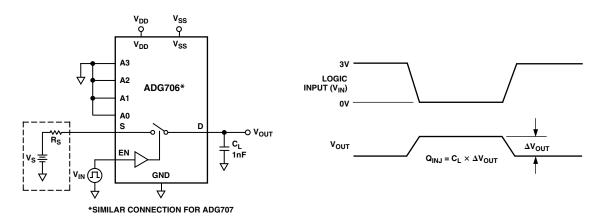


Test Circuit 6. Break-Before-Make Delay, t<sub>OPEN</sub>

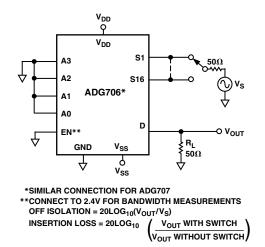
REV. B –9–



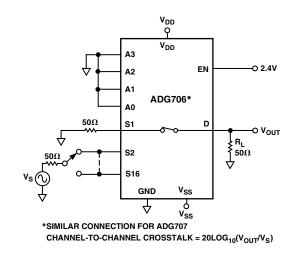
Test Circuit 7. Enable Delay, t<sub>ON</sub> (EN), t<sub>OFF</sub> (EN)



Test Circuit 8. Charge Injection



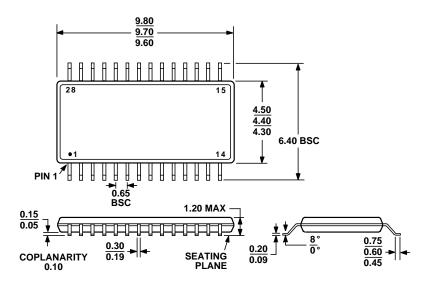
Test Circuit 9. OFF Isolation and Bandwidth



Test Circuit 10. Channel-to-Channel Crosstalk

–10– REV. B

#### **OUTLINE DIMENSIONS**



#### COMPLIANT TO JEDEC STANDARDS MO-153-AE

28-Lead Thin Shrink Small Outline Package [TSSOP] (RU-28)

Dimensions shown in millimeters

REV. B –11–

### **Revision History**

Location	Page
3/16—Data Sheet changed from REV. A to REV. B.	
Changes to ORDERING GUIDE	5
Updated OUTLINE DIMENSIONS	11
5/02—Data Sheet changed from REV. 0 to REV. A.	
Edits to FEATURES and PRODUCT HIGHLIGHTS	
Changes to SPECIFICATIONS	
Edits to ABSOLUTE MAXIMUM RATINGS notes	5
Edits to TPCs 2, 3, 4, 6–9, 12, 14	7–8
Edits to Test Circuits 9 and 10	10